

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	CHANGE OF ASSIGNEES ADDRESS
CONVEYING PARTY DATA	
Name	Execution Date
BONDTECH INC.	09/28/2009
RECEIVING PARTY DATA	
Name:	BONDTECH INC.
Street Address:	1-25, Nishinohata, Okubo-cho, Uji-shi
City:	Kyoto
State/Country:	JAPAN
Postal Code:	611-0033
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12819442
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Total Attachments: 1 source=00876030101_Request_for_Corrected_Recordation_of_Assignment_document#page1.tif	

CH \$40.00 12819442

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: SUGA, et al.)	Confirmation No: 1092
)	
Application No.: 12/819,442)	Group Art Unit: 2811
)	
Filed: June 21, 2010)	

For: JOINING METHOD AND DEVICE PRODUCED BY THIS METHOD AND JOINING UNIT

United States Patent and Trademark Office
Assignment Division
Office of Public Records
P.O. Box 1450
Alexandria, Virginia 22313-1450

**REQUEST FOR CORRECTED NOTICE OF RECORDATION
OF ASSIGNMENT DOCUMENT**

Sir:

I/We (Assignee) hereby request that a correction be made to the Notice of Recordation of Assignment Document recorded on June 21, 2010 at Reel/Frame: 024566/0289 for the above referenced patent application. A copy of the Notice of Recordation of Assignment Document and the Assignment as filed are enclosed.

I/We (Assignee) certify that Bondtech Inc.'s address should be changed from "Keihanna Plaza Labo-To, 1-7, Hikari-Dai, Seika-Cho, Soraku-Gun, Kyoto, Japan 619-0237" to "1-25, Nishinohata, Okubo-cho, Uji-shi, Kyoto, 611-0033, Japan" effective Sep 28, 2009.

Respectfully submitted,

Akira Yamauchi

Name

President

Title

Bondtech Inc.